



## small processors solve **BIG PROBLEMS**

Chris Rowen  
Founder and CTO  
Tensilica, Inc.

10 May 2011



# Agenda

---

- Four defining trends for the silicon universe
- Rethinking microprocessor design
  - World's shortest history of microprocessor design
  - Building microprocessors to order – configurability and extensibility
- Going ultra-small
- Some extreme processor applications
  - A Server with Thousands of Processors per Chip?
  - The World's Fastest DSP
  - 1,000,000,000,000 RISC ops/s in 1mm<sup>2</sup> (Turbo Decoder)
  - Putting Up To 250M Processors to Work - Exascale Climate Modeling
- Long-term Trends



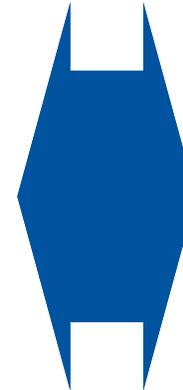
# Our New World



Mobile Broadband Terminals  
(and sensors)



Network Infrastructure



The Computing Cloud

What's impressive:

- # users
- compute per watt

What's impressive:

- Aggregate bandwidth
- bits per Hz of spectrum

What's impressive:

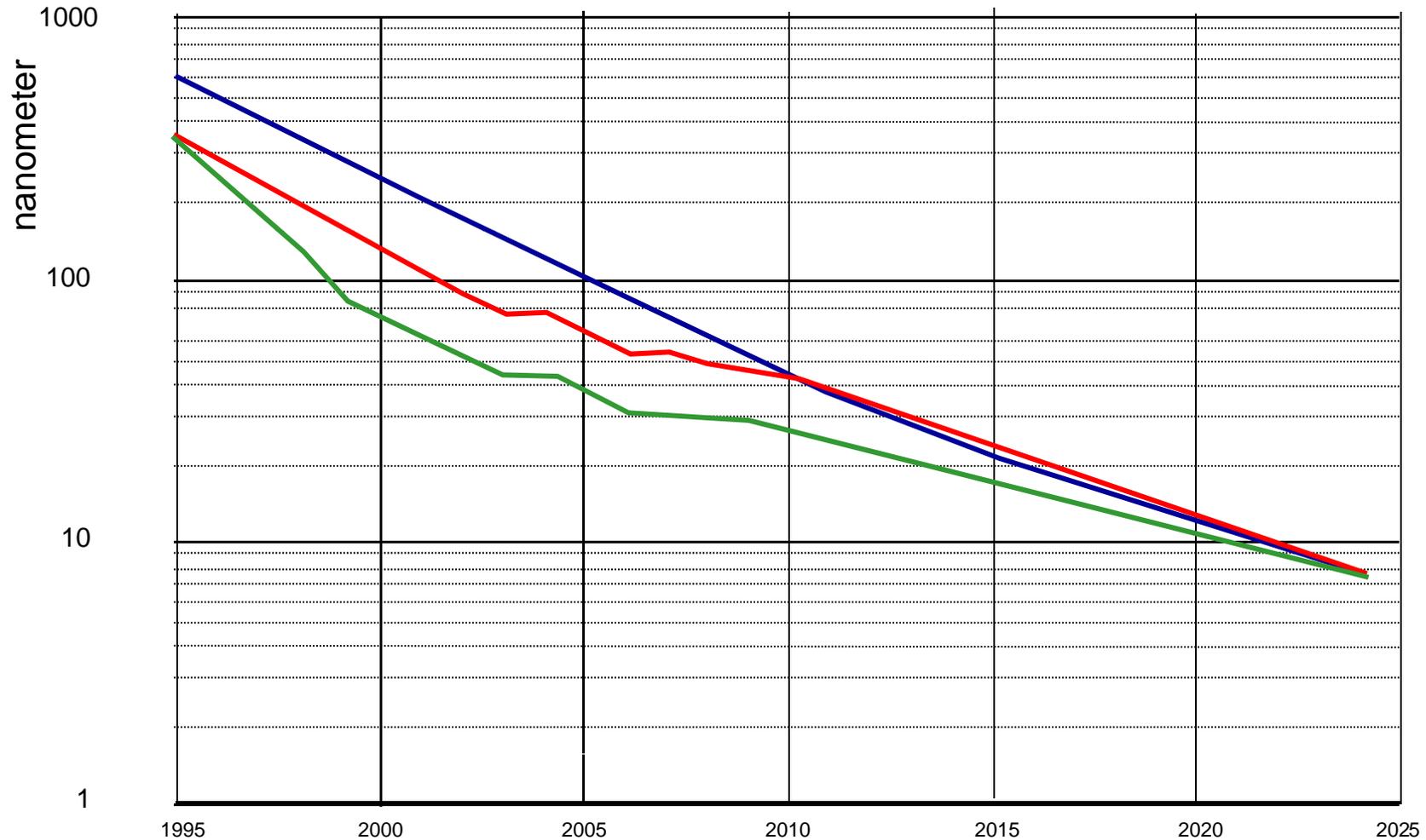
- Task parallelism
- Amount of data

# Trend #1: Silicon Density Keeps Improving

## Implication: High complexity chips cost-effective



2009 ITRS MPU/ASIC Metal 1 half pitch  
2009 ITRS MPU Printed Gate Length  
2009 ITRS MPU Physical Gate Length

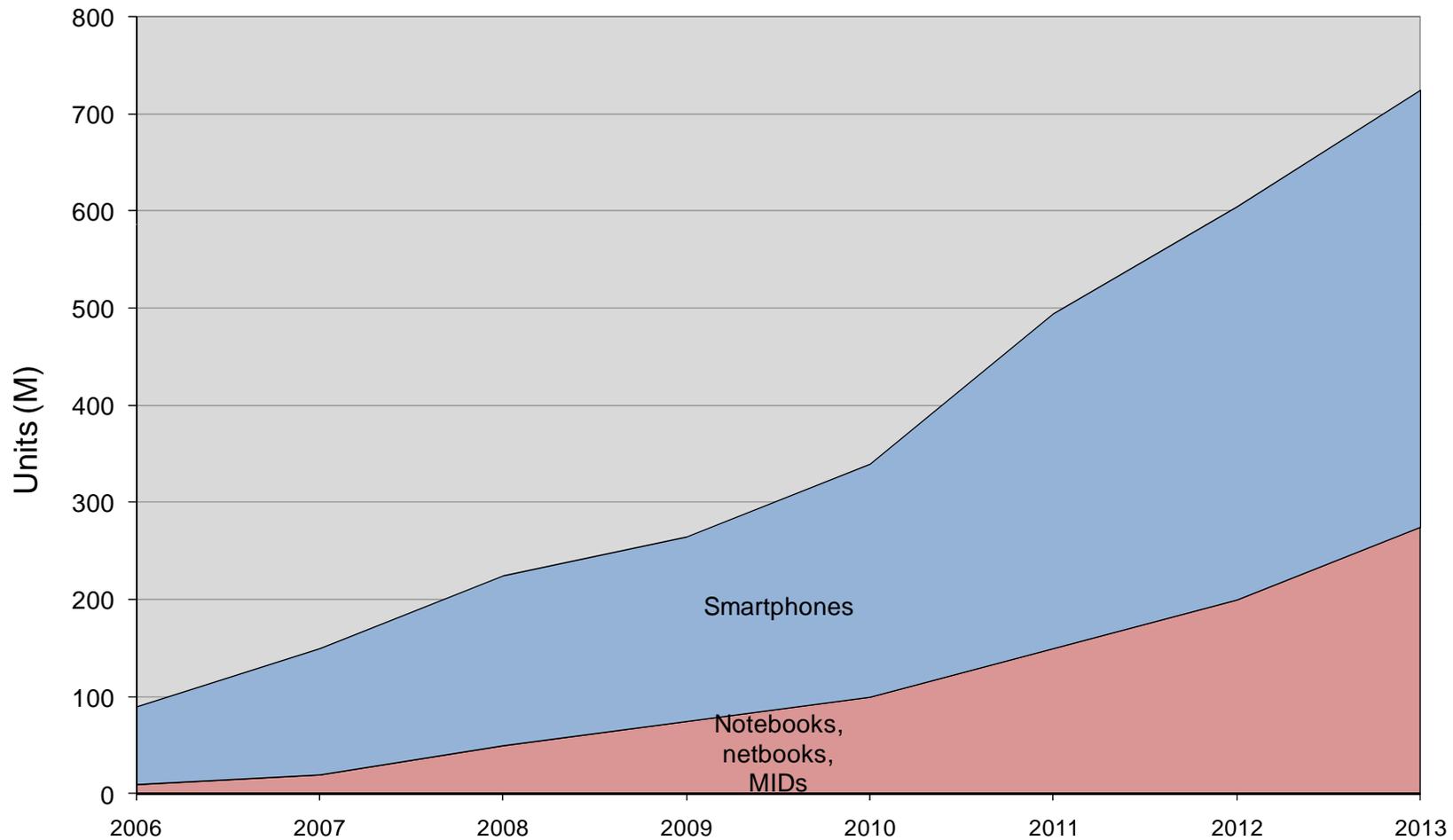


# Trend #2: Mobile Internet Unit Growth

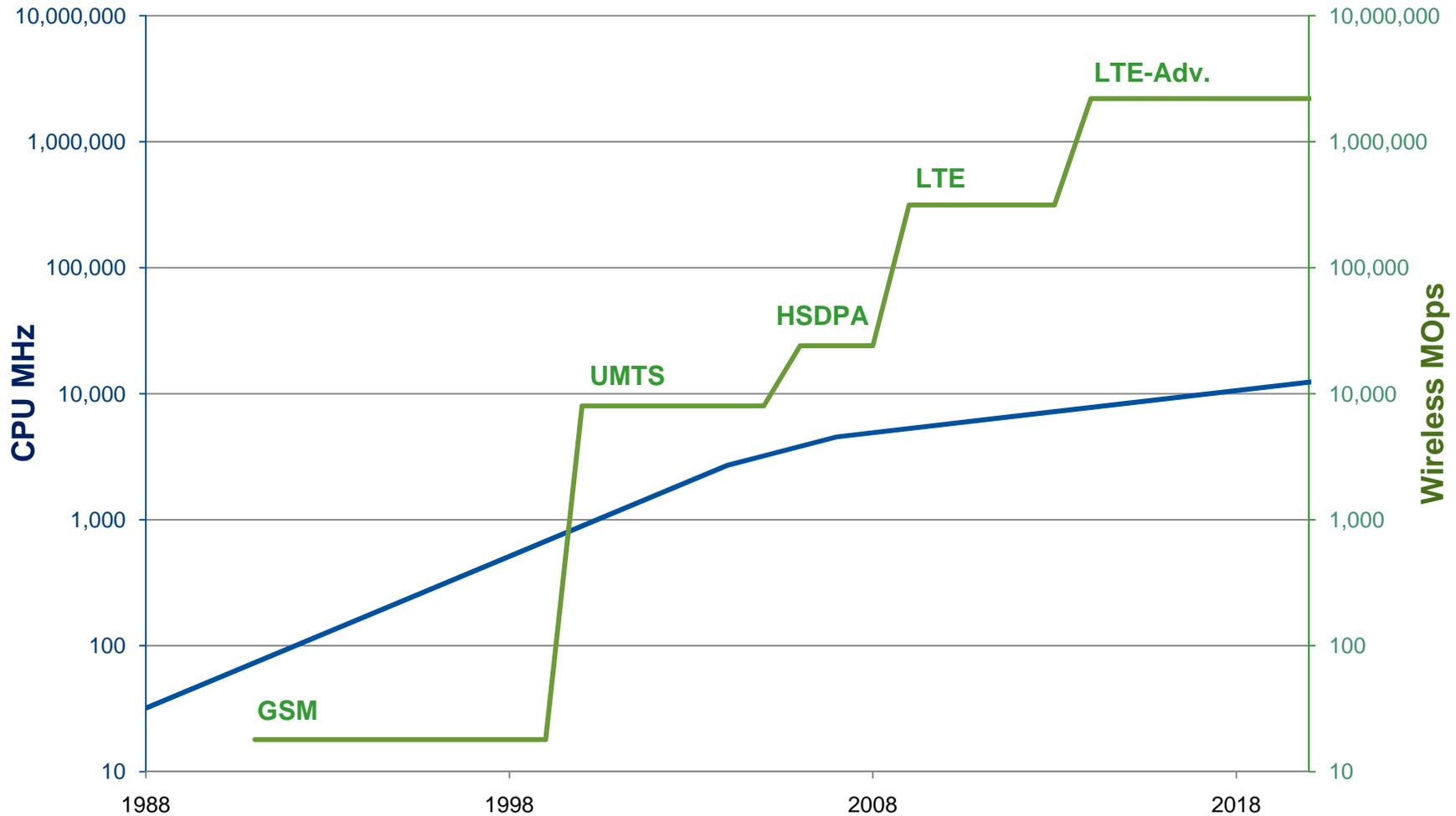
## Implication: Plenty of Silicon Demand



Mobile Broadband Terminal Units



# Trend #3: Silicon Speed Can't Keep Up with Demand

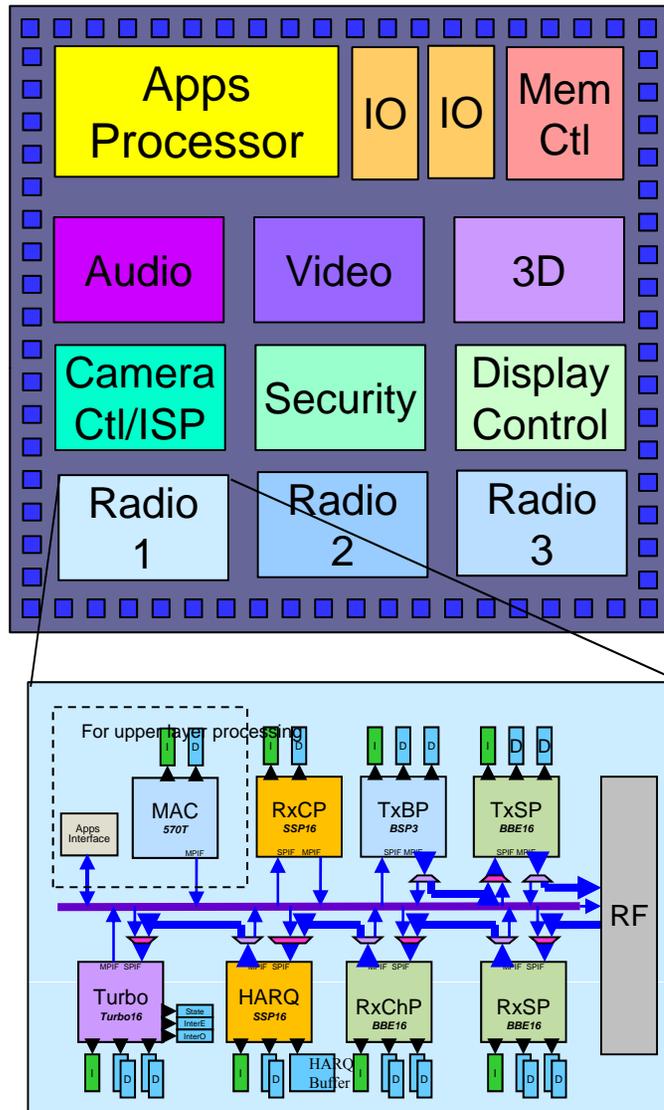


CPU MHz: ITRS Roadmap 1999, 2001, 2009

Wireless Ops: Multi-Core for Mobile Phones: C.H van Berkel, ST-NXP Wireless DATE09

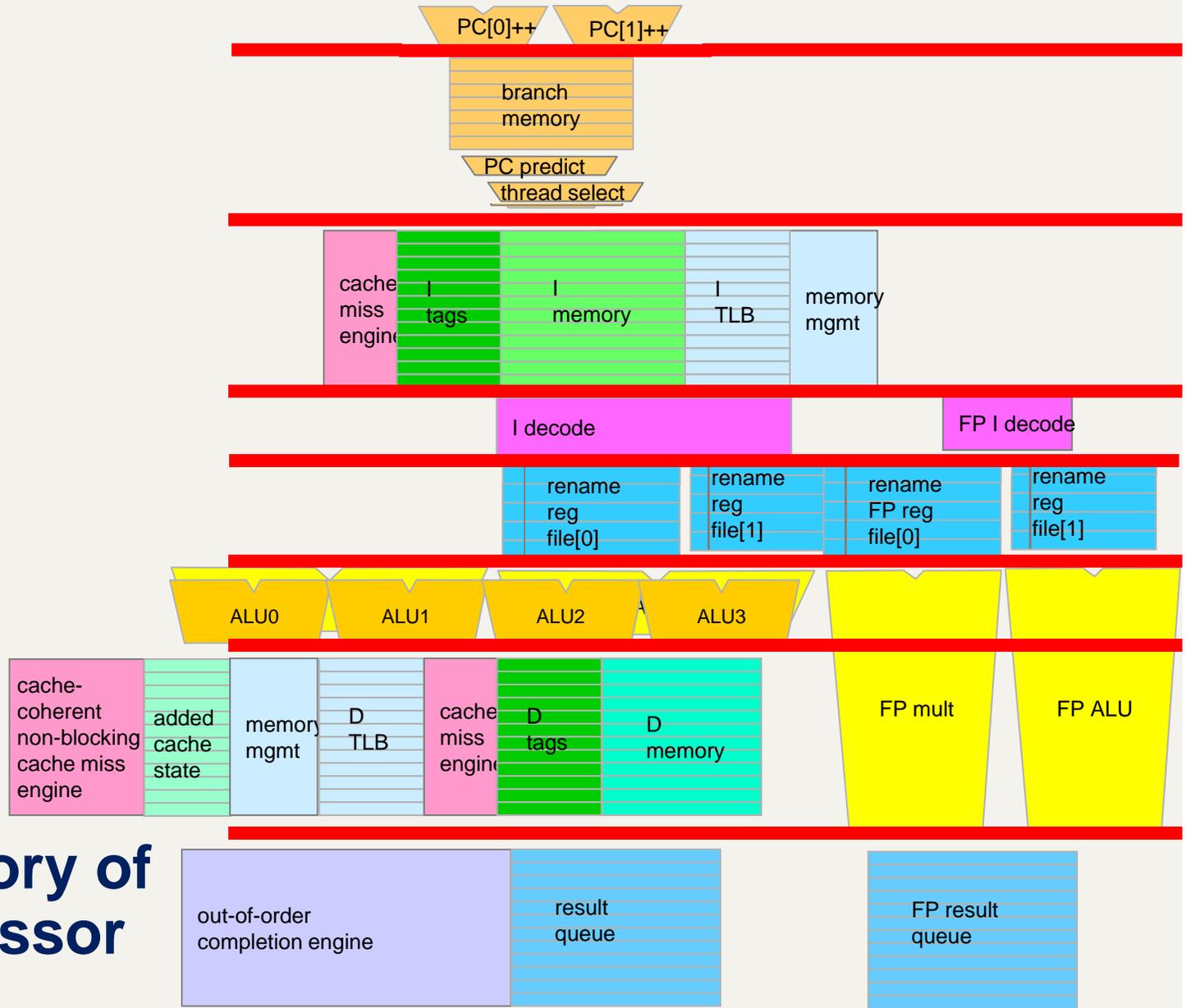
Copyright © 2011, Tensilica, Inc.

# Trend #4: System On Chip: “integrate or die”



- A platform built for an application segment → flexible within target domain
- An ensemble of subsystems, each:
  - developed independently
  - programmable
  - multi-core
- Wide variation in subsystems
  - fundamental data-types & ops
  - memory requirements
  - rate of change
- Requires systematic integration
  - Common programming
  - Common system modeling and verification
  - Common interconnect
  - Common performance, power estimation
  - Common VLSI flow

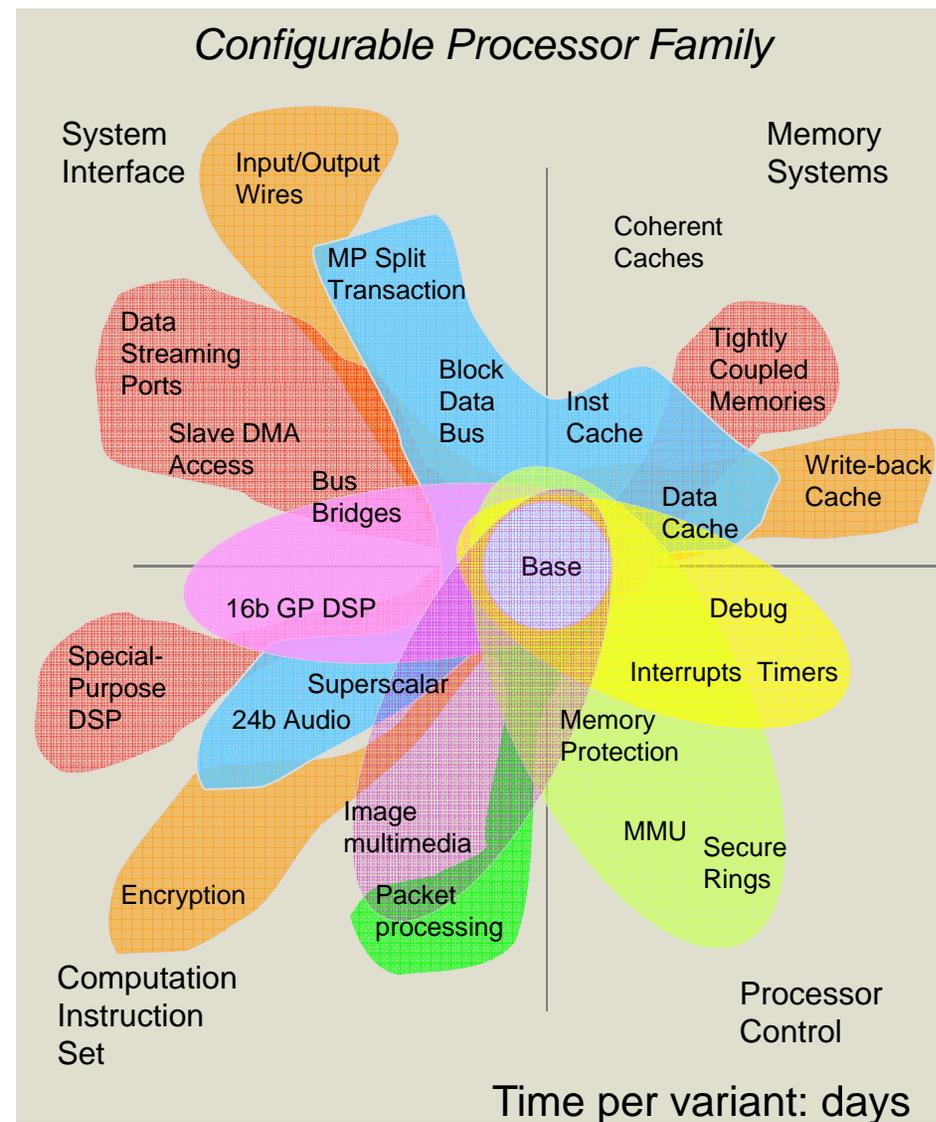
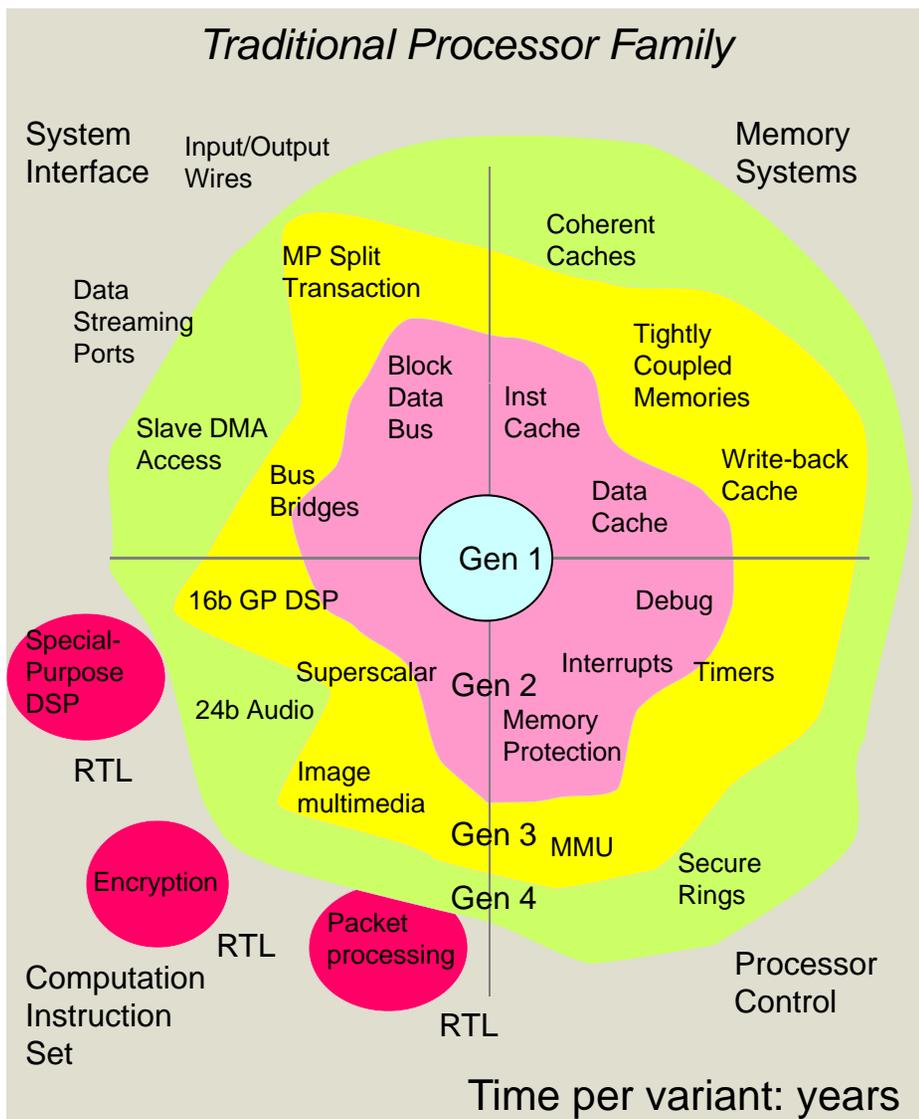
- Basic micro-controller
- Micro-code
- Data width: 4→8→16→32...
- General register file
- Cache and memory protect
- Pipelined load/store arch
- Floating point
- Superscalar (static or dyn.)
- SIMD multimedia ALU
- Branch prediction
- Symmetric multi-processing
- Out-of-order execution
- Simultaneous multi-thread



# A short history of micro-processor design



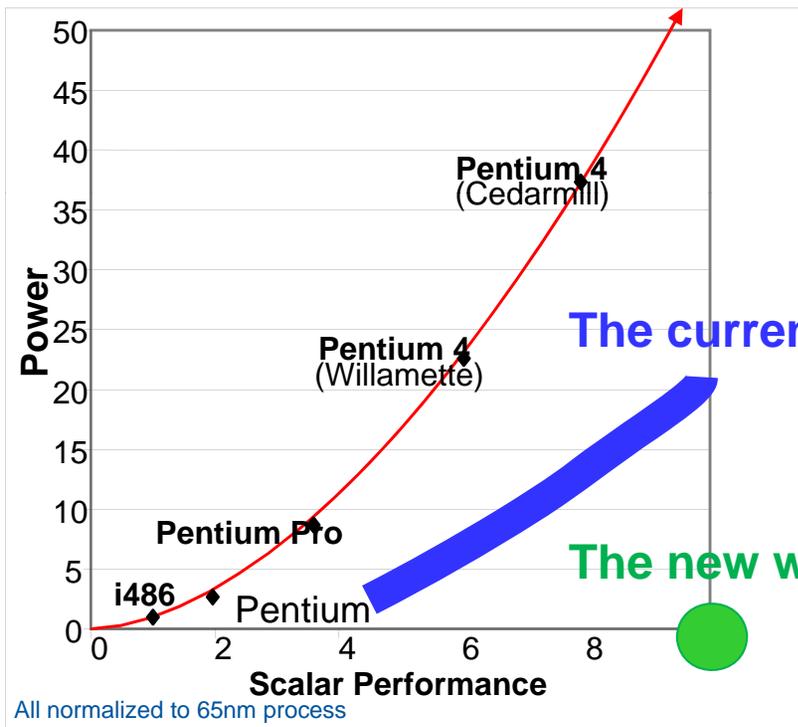
# Two models of processor evolution



# Where is processor power going?

$$\text{Power} = \text{Performance}^{1.75}$$

The old way



- Pursuit of maximum generic uni-processor performance means
    - deeper pipeline
    - minimum latency memory
    - more logic speculation
- ➔ *More wasted energy*

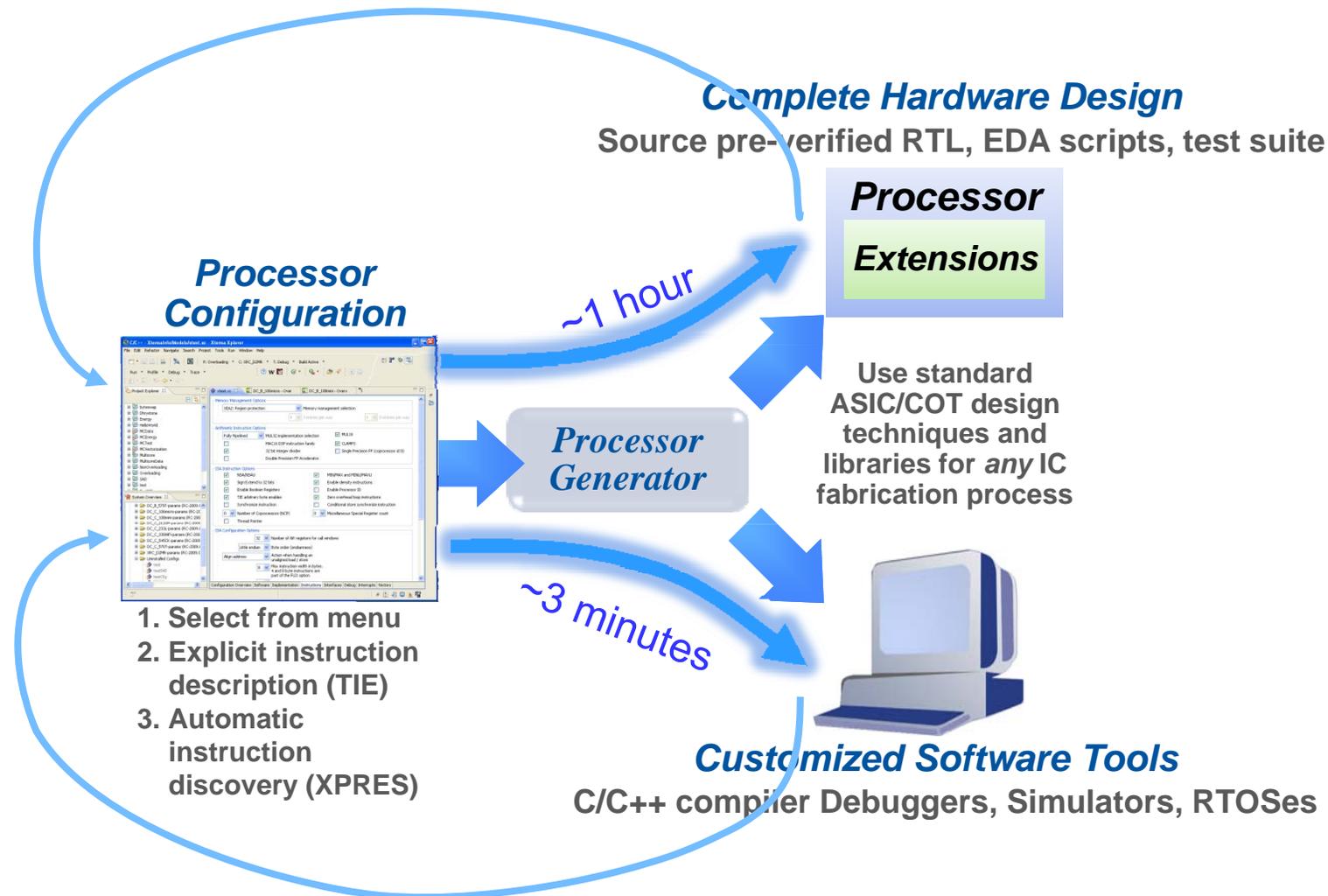
- More energy-sensitive processor design has gained traction for both high-end and mobile applications
- What's the next quantum step?

Source: John Paul Shen, Intel Microarchitecture Research Lab  
 WCED Panel: June 18, 2006



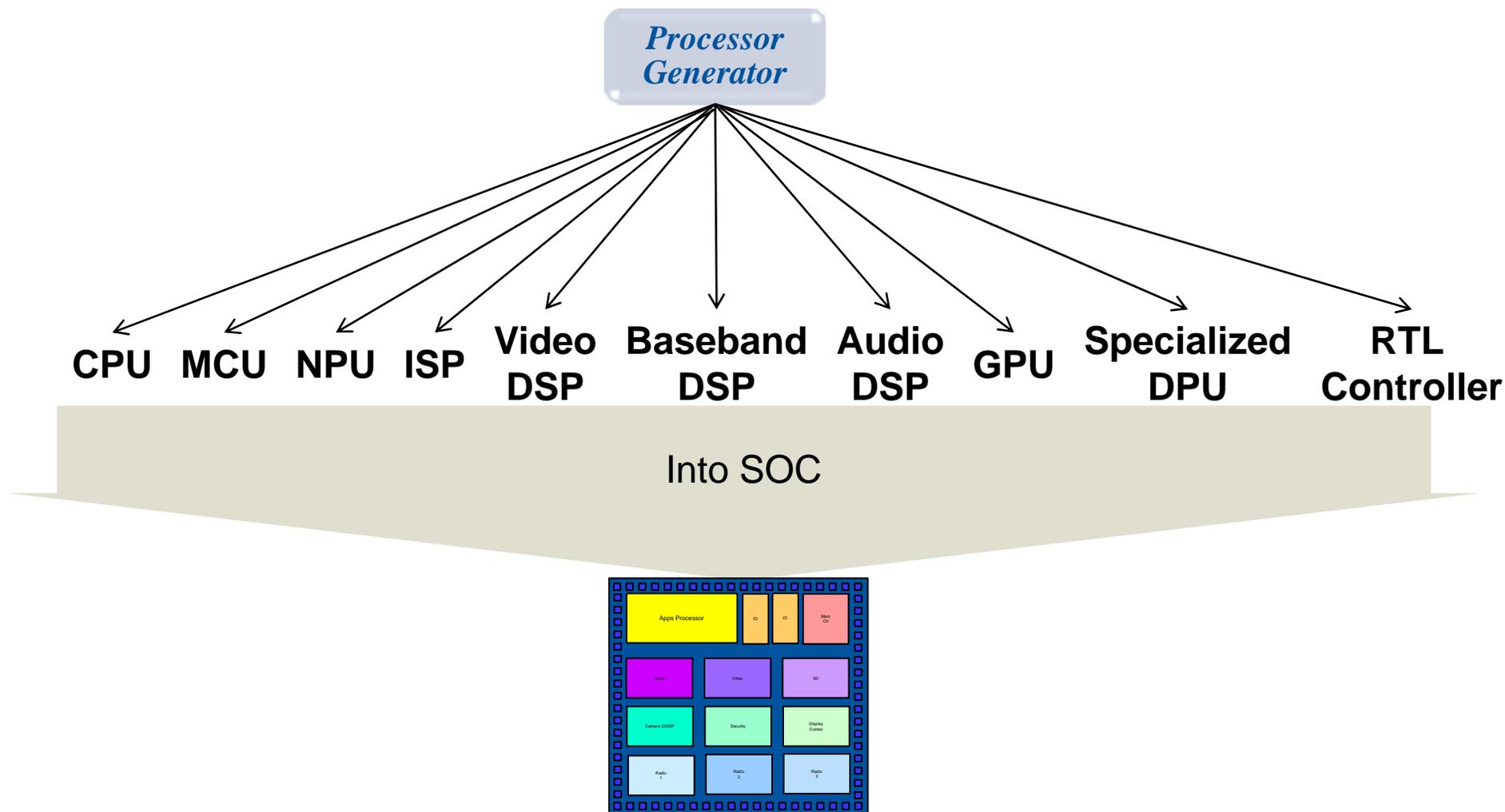
# Processor Automation → Agility and Consistency

## Xtensa Processor Generator



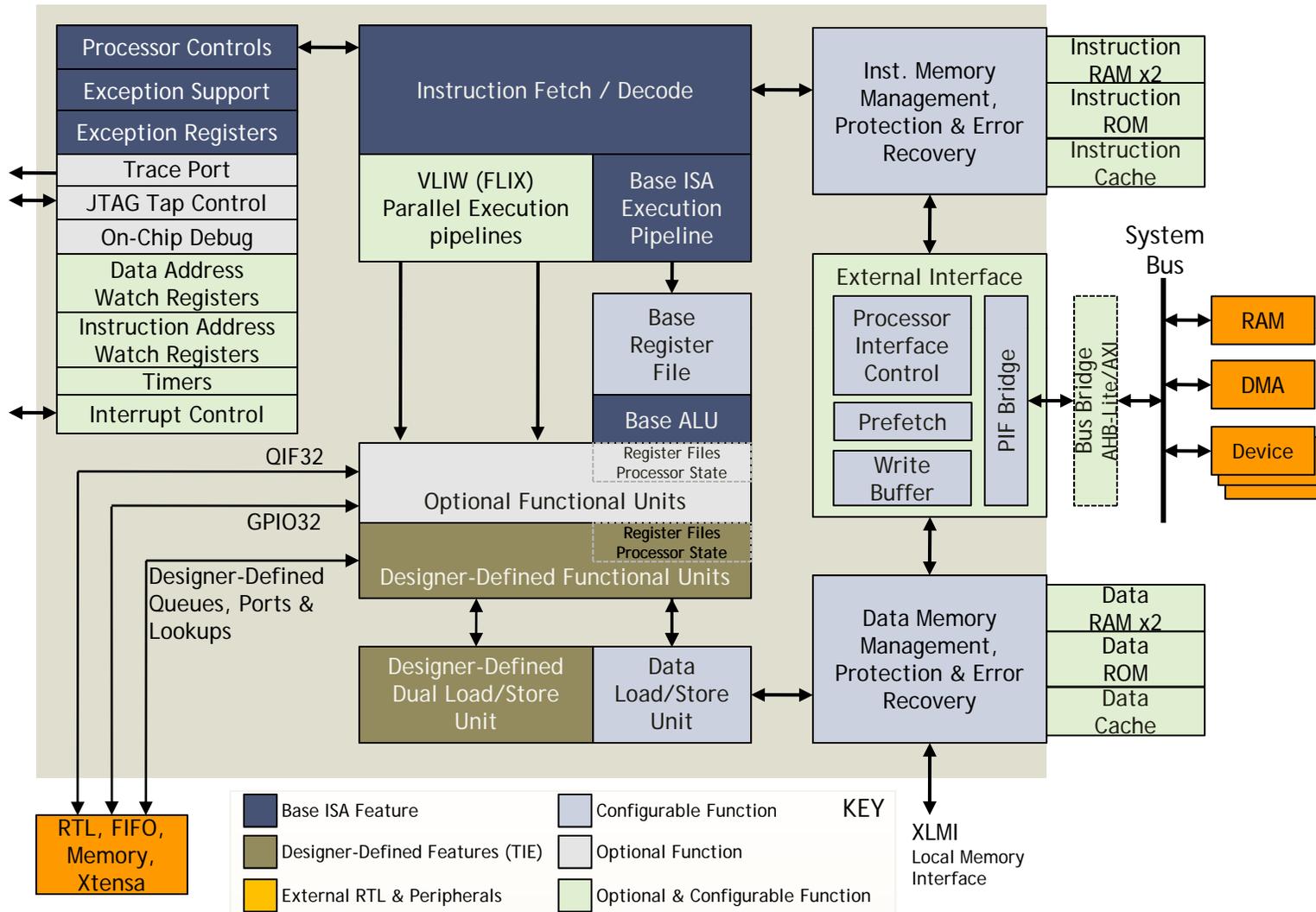


# Key ingredient for “alphabet soup”



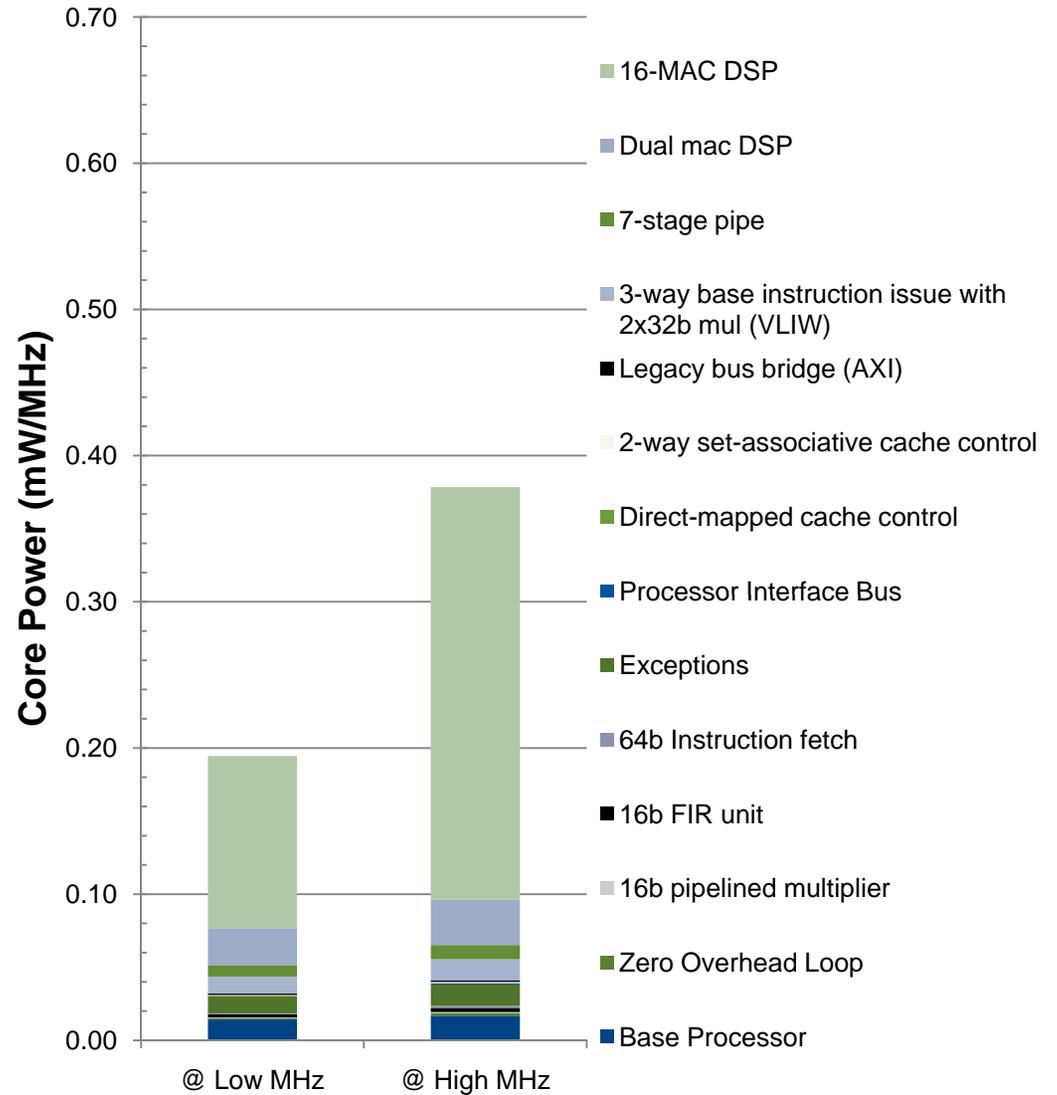
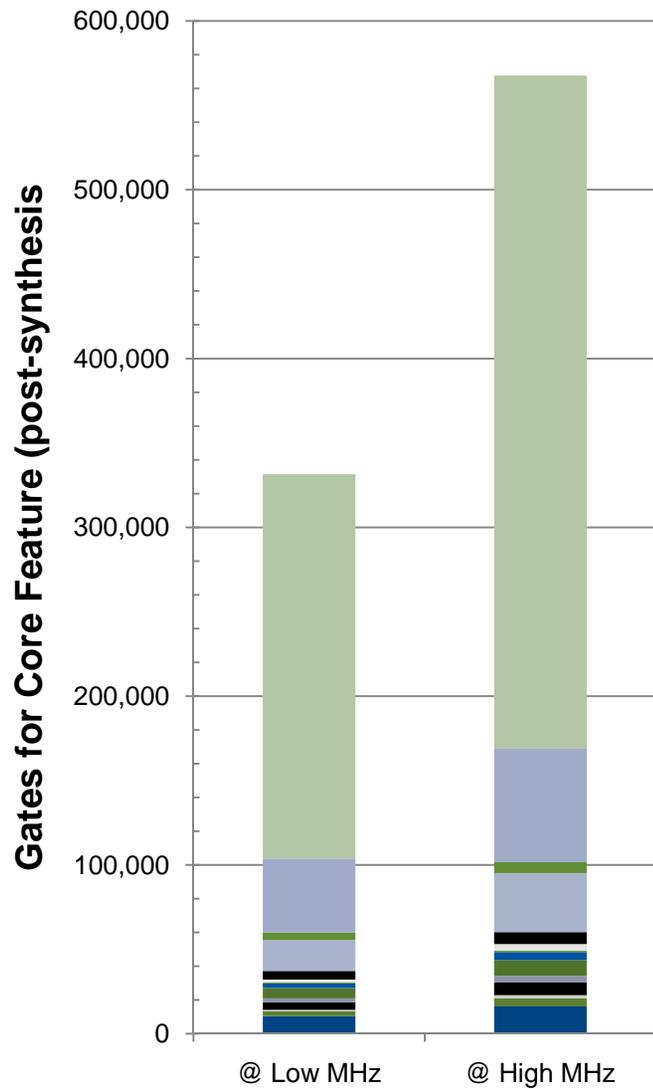
# What's Inside An Extensible Processor?

## LX4 Block Diagram



# The real cost of processor features

40LP process





# What I mean by “configurability”

## Menus of options

### *Simple menus of options*

- From fine tuning of performance, power and area
  - Size, type, width and access latency of memories
  - Load/Store unit characteristics
  - Number of general purpose registers
  - Number and priority levels of interrupts
  
- To high-level, market-specific building blocks
  - Common functional units:
    - Floating point, multiplier, divider, NSA
  - Complex application engines:
    - HiFi2 Audio DSP
    - 16-MAC ConnX BBE16 DSP
    - Dual-MAC ConnX D2 DSP

**Memory Management Options**

XEA2: Region protection  Memory management selection

4  I-entries per way      4  D-entries per way

---

**Arithmetic Instruction Options**

Fully Pipelined  MUL32 implementation selection

MAC16 DSP instruction family       MUL16

32 bit integer divider       CLAMPS

Double Precision FP Accelerator       Single Precision FP (coprocessor id 0)

---

**ISA Instruction Options**

NSA/NSAU       MIN/MAX and MINU/MAXU

Sign Extend to 32 bits       Enable density instructions

Enable Boolean Registers       Enable Processor ID

TIE arbitrary byte enables       Zero overhead loop instructions

Synchronize instruction       Conditional store synchronize instruction

0  Number of Coprocessors (NCP)      0  Miscellaneous Special Register count

Thread Pointer

---

**ISA Configuration Options**

32  Number of AR registers for call windows

Little endian  Byte order (endianness)

Align address  Action when handling an unaligned load / store

8  Max instruction width in bytes.  
4 and 8 byte instructions are part of the FLIX option

5  Pipeline length

---

**DSP Coprocessors**

Vectra LX DSP coprocessor instruction family

VectraVMB: Extra DSP Instructions  
Vectra adapts to match the number of configured Load/Store units

ConnX D2 DSP

---

**HiFi2 Audio Coprocessor**

HiFi2 Audio Engine DSP coprocessor instruction family

HiFi2 32x24-bit MAC extensions

---

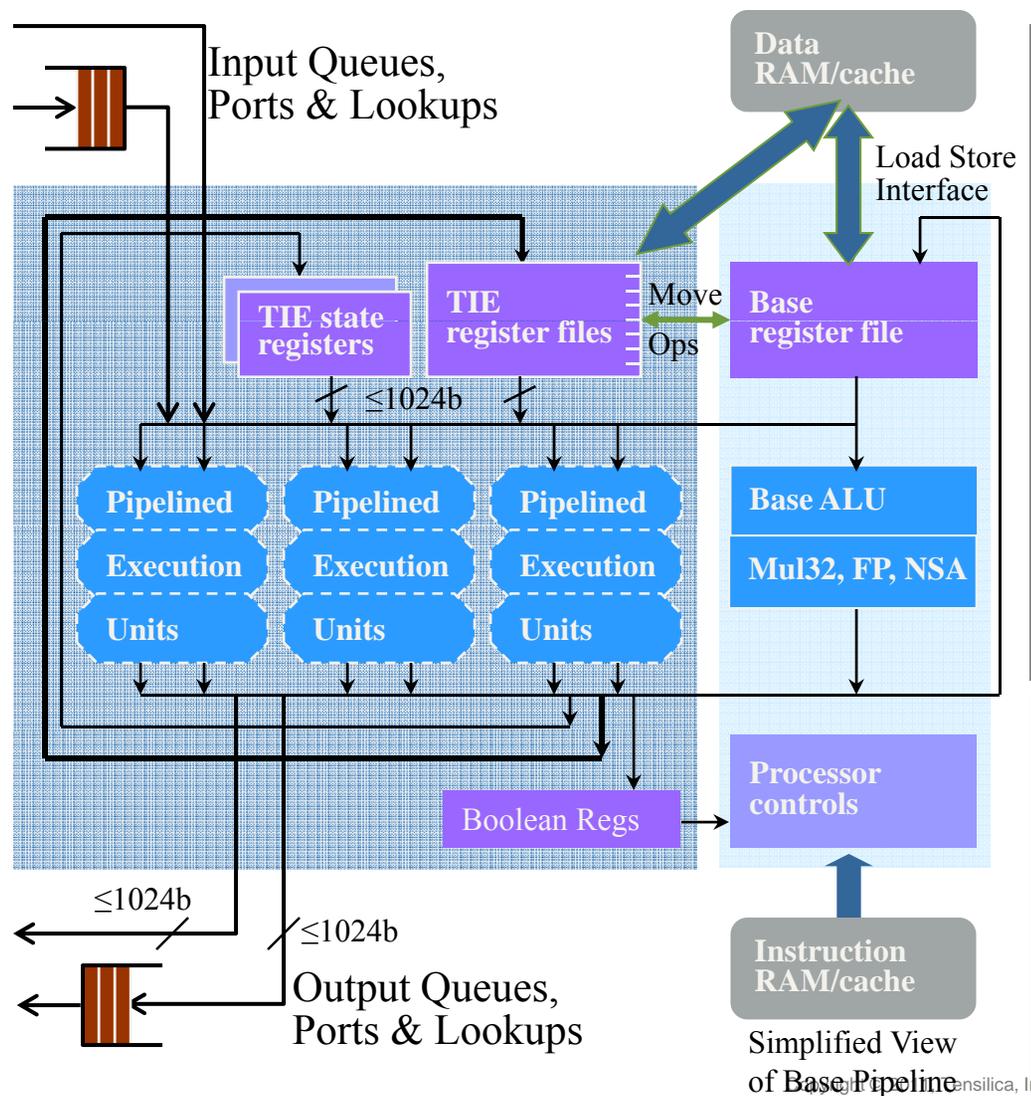
**Fixed Core Extensions**

FLIX3: 3-way FLIX



# What I mean by “extensibility”

Base processor + extension environment = optimized cores



1. Start with base Xtensa core
2. Add functional units from menu of config options
3. Add register files and state registers  
*Add corresponding new data types with automatic C/C++ compiler support*
4. Add up to 512-bit Load/Store instructions
5. Add multi-cycle, SIMD arithmetic and logic function units  
*Up to 64 source, destination registers*
6. Create multi-issue VLIW datapath
7. Add custom I/O ports, queues, and lookup interfaces

A simple TIE example – VLIW processor with 128b data types and operations

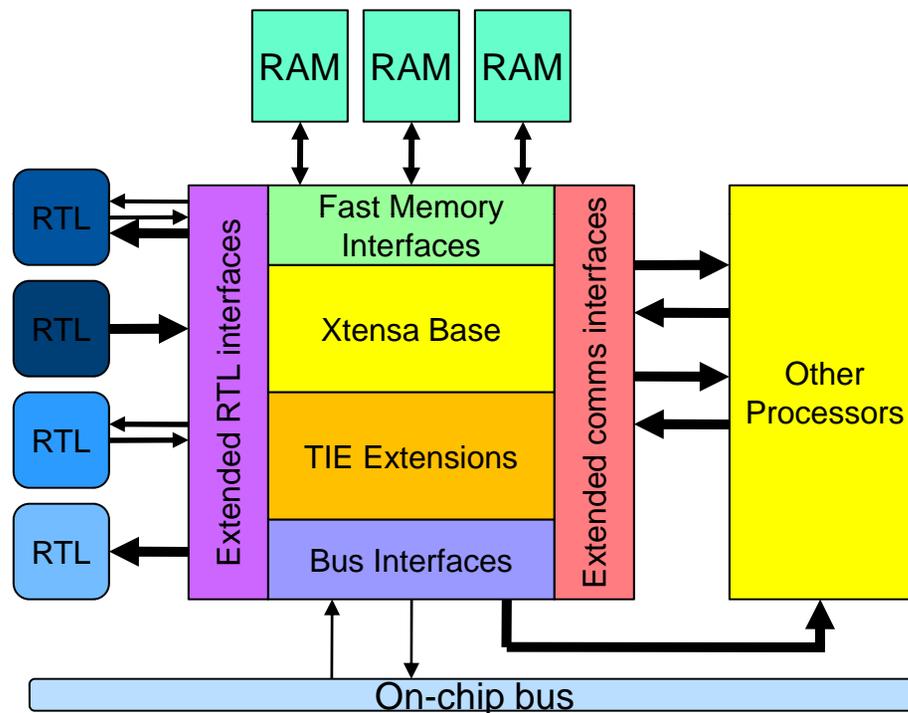
```

regfile wd 128 16 w
operation wadd {in wd a, in wd b, out wd c} {} {assign c = a + b;}
format f64 64 {ls_slot, alu_slot}
slot_opcodes ls_slot {LD.wd, ST.wd, L32I, L16UI, L16SI, L8UI, BNE, BEQ, BEQI}
slot_opcodes alu_slot {wadd, ADD, ADDI, SUB, SLL, SRL, SRA, SRAI, SLLI, AND, OR, EXTUI}

```



# Extensibility enables better multi-core

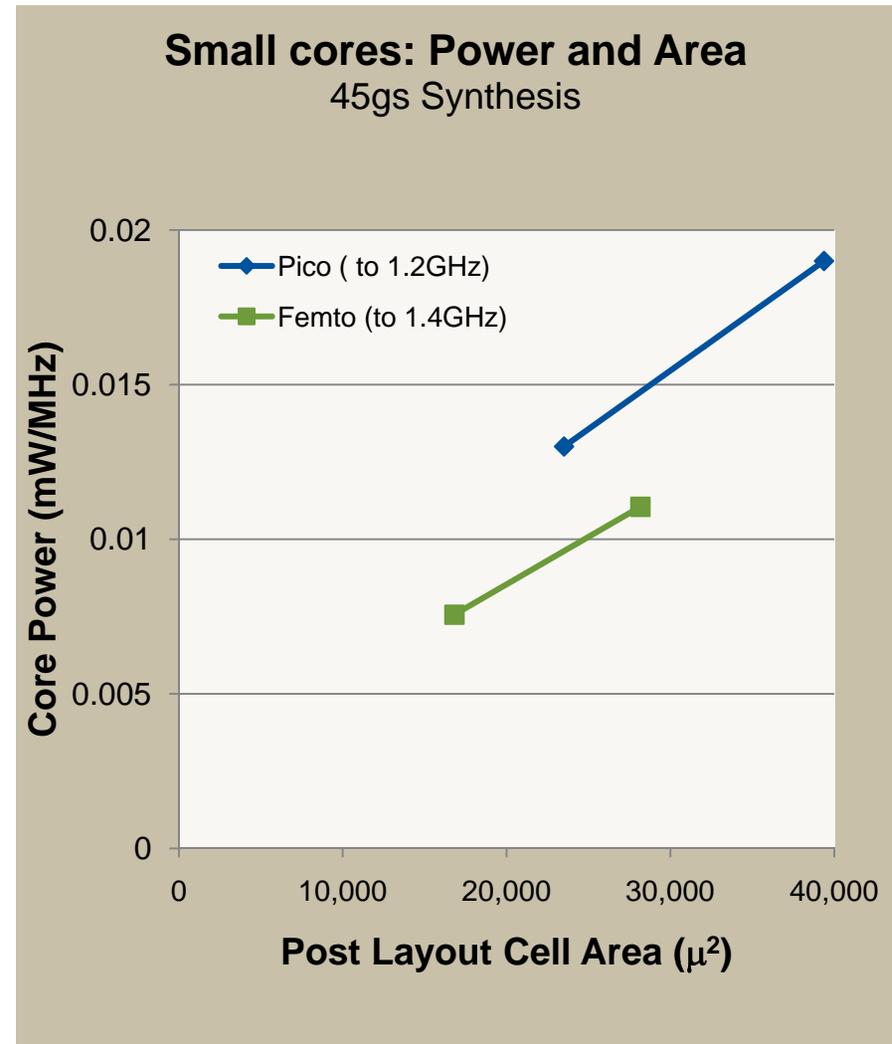


- Small base: low threshold for adding programmability
- ISA extensions: high computation efficiency
- Memory: wider and more flexible
- Standard interfaces: to buses and NOCs
- RTL interfaces: more throughput and control
- Comms interfaces: 10x mB/mW, multi-core SW libs



# Pushing the envelope on small

- What happens if you really pare down the processor to essentials
  - General-purpose 32b ISA
  - Fast 5-stage pipeline
  - Local instruction/data memories
  - Optional bus interface, interrupts and exception handling, multiply/divide, zero-overhead loops
- Example Footprint (45gs):
  - Core
  - + Byte-wide serial boot-loader
  - + 2KB/2KB memory [yes, tiny]
  - **0.052mm<sup>2</sup>** to **0.072mm<sup>2</sup>** floorplan area
  - up to ~20 cores/mm<sup>2</sup>
  - up to ~25,000 DMIPS/mm<sup>2</sup>
- Extrapolate to 22nm process:
  - ~80 cores/mm<sup>2</sup>
  - > 120,000 DMIPS/mm<sup>2</sup>





# System implications of ultra-small cores

---

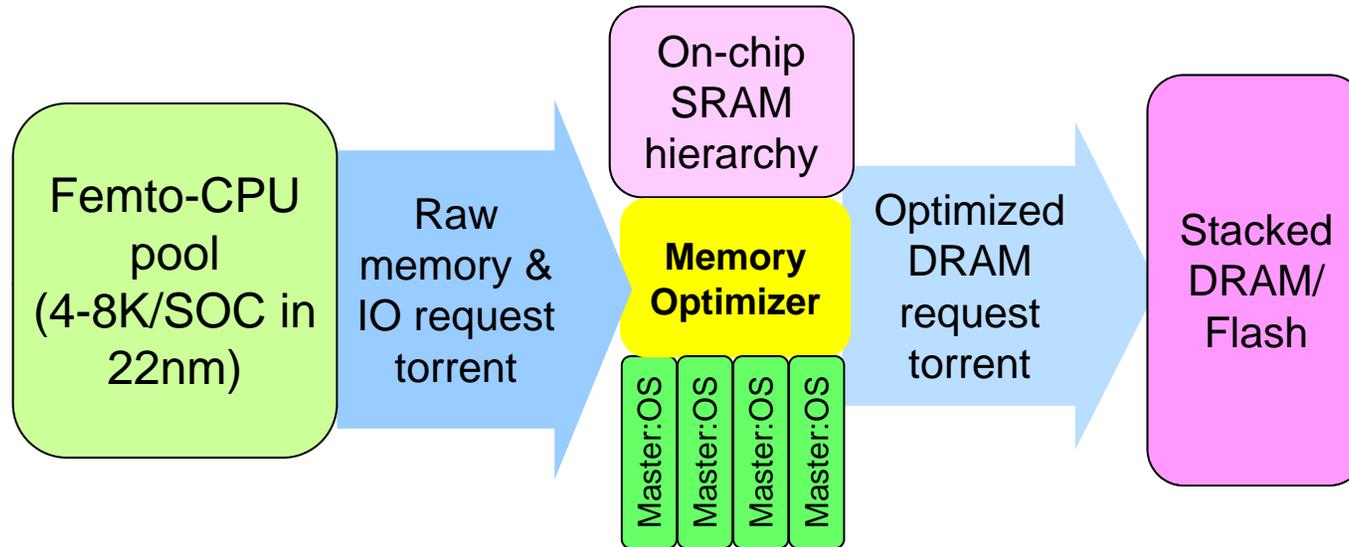
## The “new NAND gate” in embedded systems:

- Distributed intelligence:
  - Dynamic QOS in on-chip communication network
  - Finite state machine control of hardwired function blocks
  - Extended for specialized computing (graphics, signal, security) – homogeneous or heterogeneous
- Extends reach of **software+processor** ecosystem to lowest layers

## Radical building-block in energy-efficient server:

- Traditional server (wastes energy):
  - Few CPUs/chip:  $O(10)$
  - Memory optimized to minimize latency at CPU
- Minimum-energy server (wastes CPUs):
  - Very many CPUs/chip:  $O(1000)$
  - Memory optimized to minimize energy per useful MB

# Extreme Processor #1: Efficient service of memory torrent

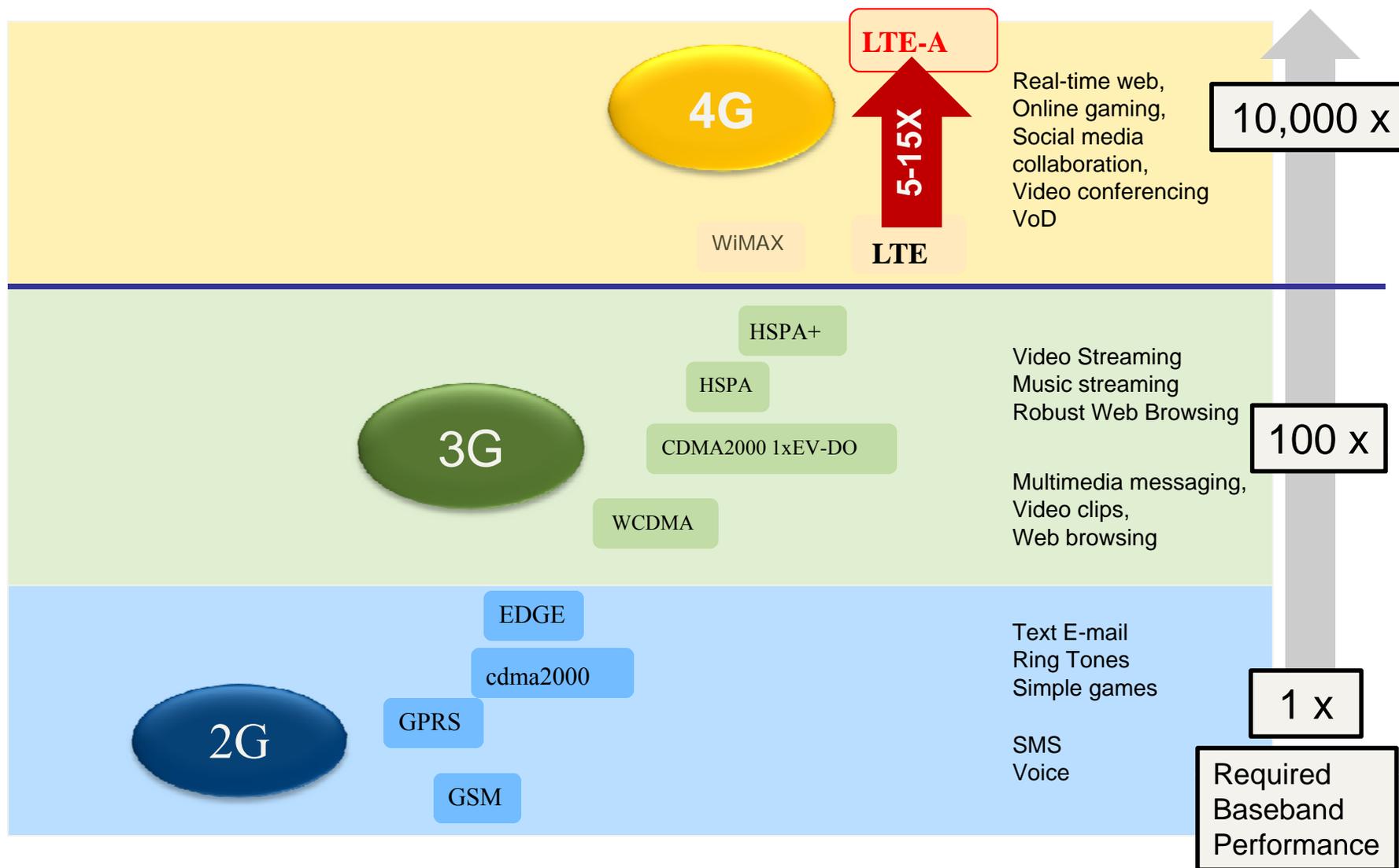


Moving from minimum latency to maximum throughput memory systems



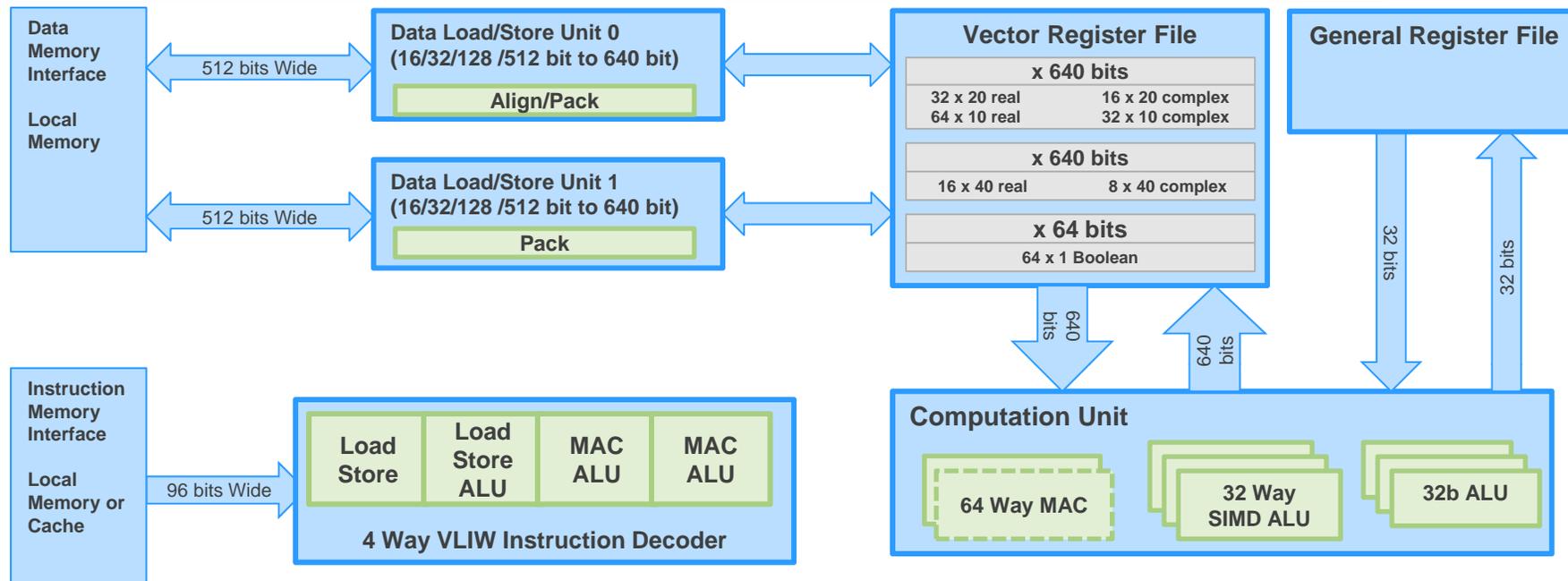
# Domain Example: 4G Wireless

## Quantum Step in Required Performance





# Extreme Processor #2: ConnX BBE64: >100 GMACS per second



## Optimized Architecture for DSP Applications

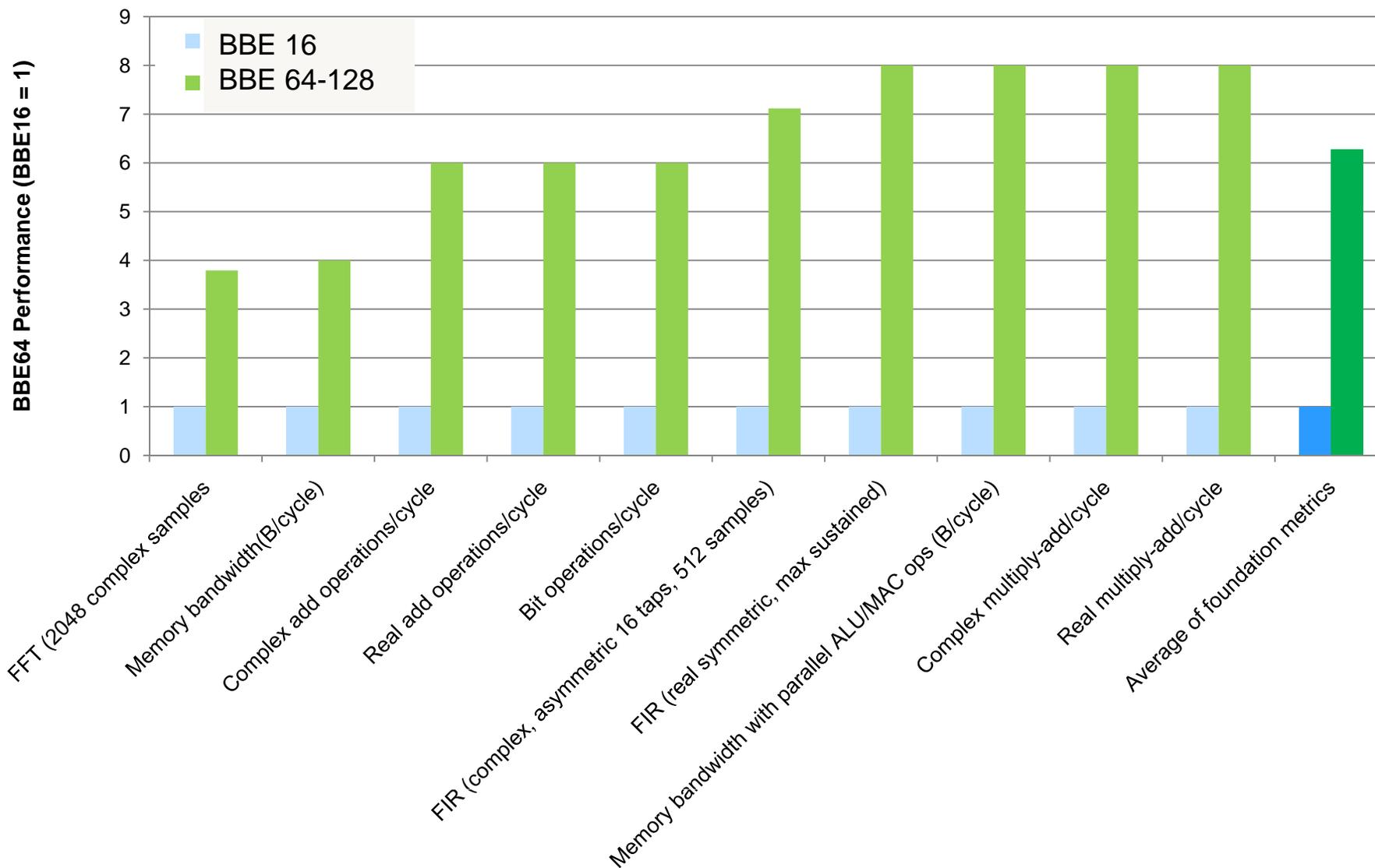
- 4-way VLIW x 32-way SIMD > 128 DSP ops/cycle
- 16/24/96b 4-issue VLIW – almost any instruction in any slot
- 128 MAC ops/cycle for matrix and filter functions
- Guard-bits on all DSP data for numerical accuracy
- Protected pipeline: interlocks/bypasses for robustness
- Support for all data types from C
  - Complex/real
  - Scalar/vector
  - Fractional/integer

## High Bandwidth Configurable Memory Subsystem Interface

- Dual load/stores with dual 512b memory interfaces
- Full bandwidth on packed and unaligned data vectors
- DMA support for local data memory
- Extensible with special memory ports
- Extensible with direct connect data queues: 4 x 640b per cycle



# About 6x gain over current leading DSP



Foundation Performance Metric

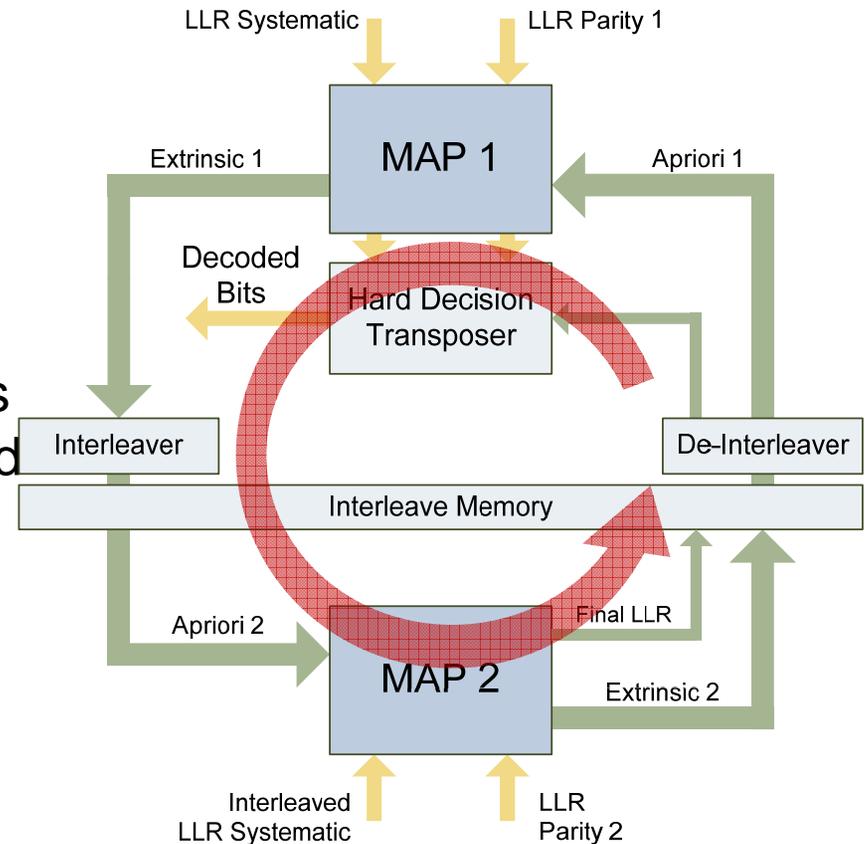
Copyright © 2011, Tensilica, Inc.

# Extreme Processor #3

## Inside a programmable Turbo decoder



- Turbo-decoding: iterative trellis decoding for near-Shannon-limit channel coding
- Rate 1/3 coding: three soft-bit streams in (data, parityA, parityB) and one hard bit stream out
- 4-8 iterations of Turbo to reach convergence
- Up to 22 memory references per cycle (HSPA+)



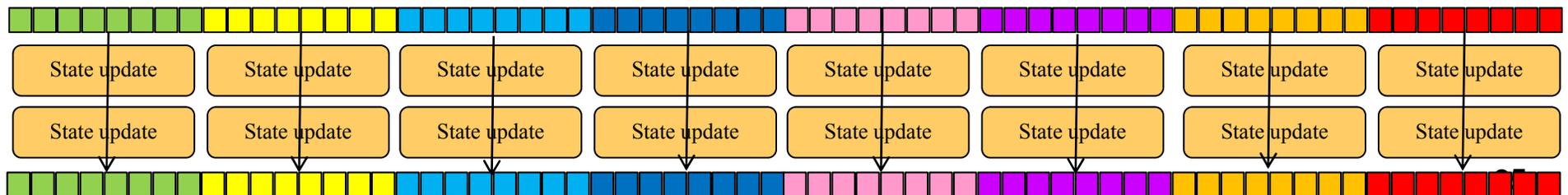


# Inside the Turbo16 Processor

## *Huge Computation Load: >1 TeraOps*

---

- Per state update:
  - ~25 RISC operations per state per bit X 8 states = ~200 ops per bit
- 8-parallel windows based decoding
  - Interleaving and de-interleaving operations integrated with load/ store operations to odd/even Data RAM
- 2 bits processed sequential per cycle:
  - X 2 bits per cycle = ~3200 ops per cycle (16 bits)
  - Also cuts state memory storage in half
- 150Mbps at 8 iterations requires ~380MHz: x 380MHz =  $1.2 \times 10^{12}$  operations per second
- Software-based early termination → lower power



# Extreme Processor #4

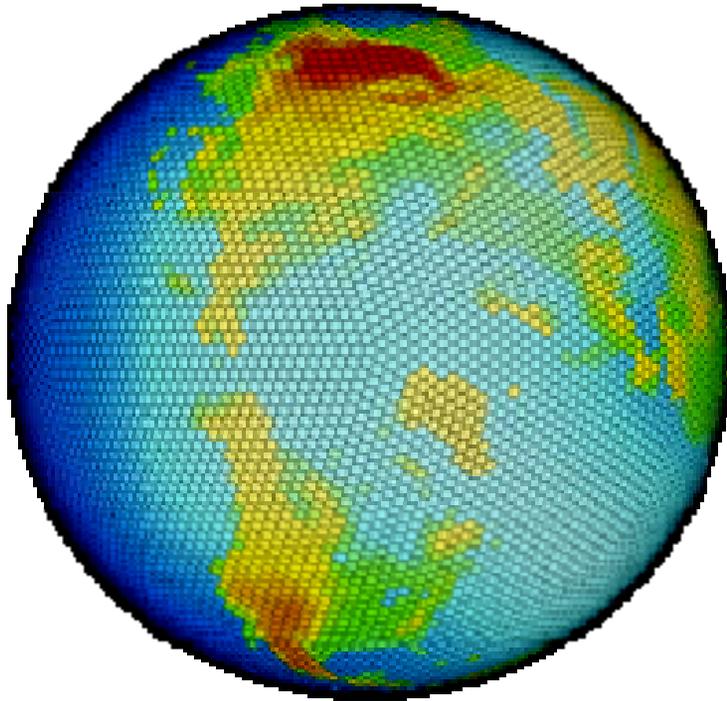
## Energy-Efficient Supercomputing



### *Lawrence Berkeley Lab Climate Modeling System*

Lenny Oliker and Michael Wehner of Lawrence Berkeley Lab  
target: a much more parallel climate model

- 1.5km grid for Earth
- 20,000,000 domains @ 500 MFLOPS + 500 MB/s per domain + 20MB/s 2D mesh communications
- Complex algorithms require general-purpose programmability in double precision floating point



#### ■ Technical/ Economic Challenges

1. Variance in data-reference/ communication patterns for codes
2. Potential for extreme scalability via large-scale processing arrays
3. Size, capital and operating costs strongly correlated to system power dissipation
4. General-purpose CPUs optimized for integer applications – unimpressive performance per \$, per watt

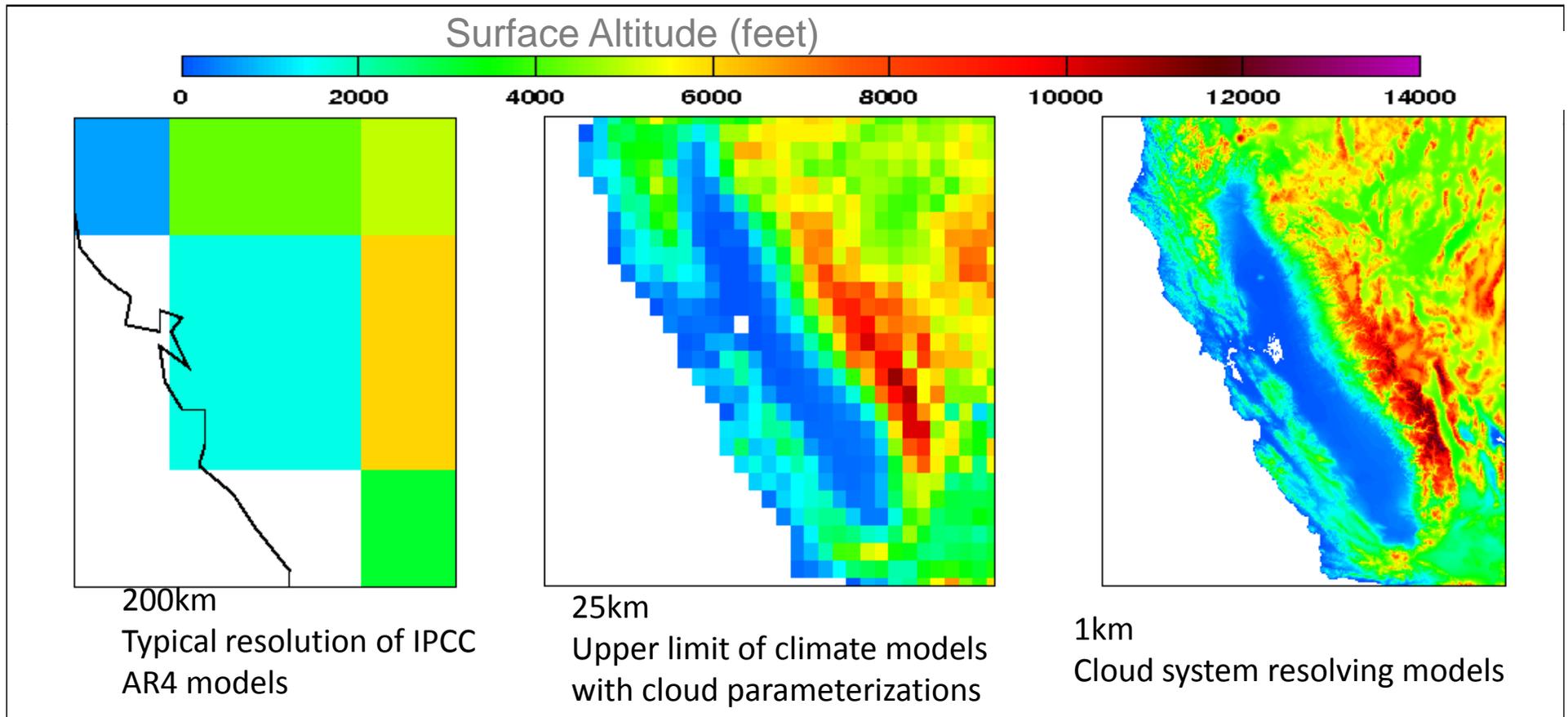
See: <http://www.lbl.gov/Science-Articles/Archive/NE-climate-predictions.html>

# Climate Modeling System

## Global Cloud System Models: A Transformational Change



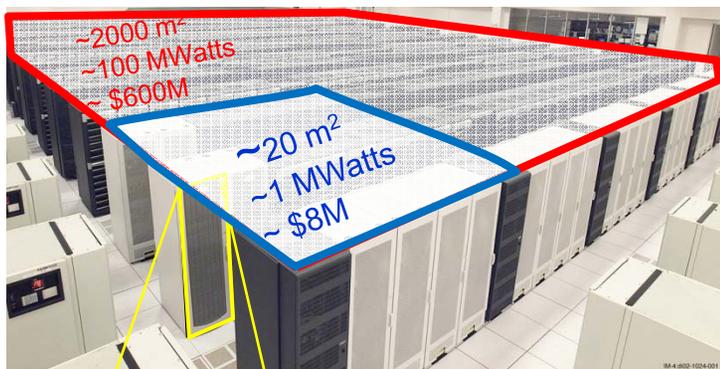
- Cloud formation is critical effect in climate
- Model accuracy goes up dramatically at km-scale grid
- Higher resolution model requires 10-100 peta-flop systems





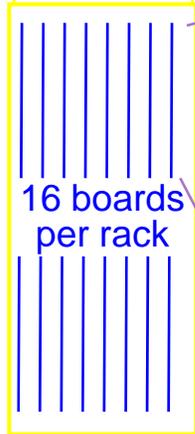
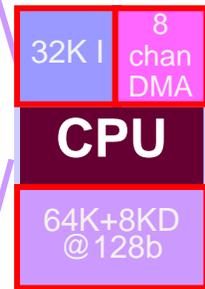
# LBNL "Green Flash" Architecture: 10 PetaFLOPS System @ 2.5M CPUs → 250M CPUs

ExaFLOP almost in reach

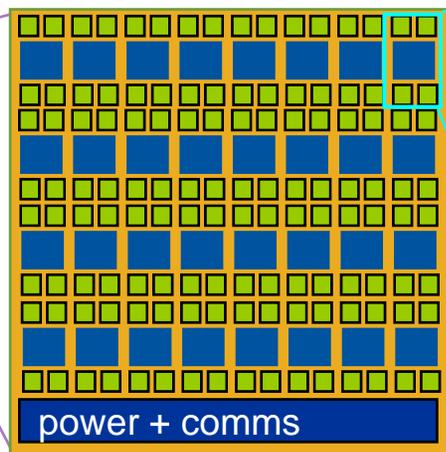


## VLIW CPU:

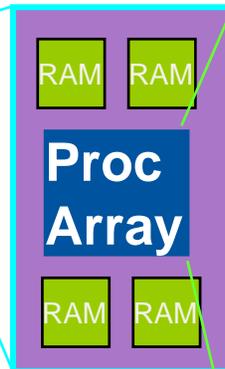
- 128b load-store + 2 DP MUL/ADD + integer op/ DMA per cycle:
- Synthesizable at 1GHz in commodity 28nm
- 0.25mm<sup>2</sup> core, 0.7mm<sup>2</sup> with inst cache, data cache data RAM, DMA interface, 0.15mW/MHz
- Double precision SIMD FP : 4 ops/cycle (4 GFLOPs)
- Vectorizing compiler, lightweight communications library, cycle-accurate simulator, debugger GUI
- 8 channel DMA for streaming from on/off chip DRAM
- Nearest neighbor 2D communications grid



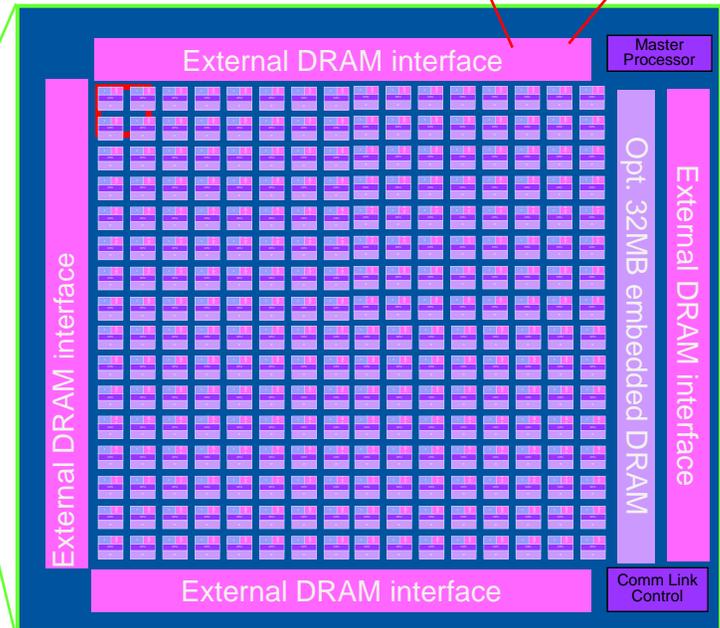
19 racks @  
~55KW



32 chip+memory  
clusters per board (32  
TFLOPS @ 2900W



8 DRAM per  
processor  
chip:  
100 GB/s



256 processors per 28nm chip  
>1 TeraFLOPs @ 60W

## Wrap up:

### *Looking at long-term silicon and system trends*

---

#### **1. Continued fixation on energy for mobility and cost:**

- memory access cost >> computing cost
- mW per [useful] MBps most relevant metric

#### **2. Parallelism in cloud >> parallelism in terminal devices:**

- massive ~homogeneous servers take increasing fraction of compute
- terminal devices dominated by access (radios) and presentation (media)

#### **3. Expertise in data-intensive real-time functions essential to leading in volume markets:**

- wireless/DSP
- multimedia: audio, video, imaging/recognition, graphic/rendering

#### **4. “Sea-of-processors” SOC design increasingly real:**

- design simplicity with processor generation
- greater technical and market flexibility



# Warning: Advertisement

## Tensilica At A Glance

- **Business Model:** Licensing of “Dataplane Processor Unit” IP to semiconductor and system OEM SoC design teams
- **Customers:** 160+ companies, including 2/3 of top semiconductor manufacturers
- **Focus Markets:** Mobile Wireless and Home Entertainment
- **Products:**
  - *ConnX Baseband Engines for Wireless: BBE16, BBE64, D2, SSP16, BSP3, Turbo16 + software*
  - *HiFi Audio DSPs: 330HiFi, HiFi2, HiFi2 EP*
  - *Xtensa Processor, Processor Generator and Software Environment*
- **Volume:** >500M cores/year, fastest architecture to 1B cores
- **Company status:** Largest privately-held IP firm, profitable

